

### Description

The 4942–4944 *Sn100e RA Solder Wire* is an electronic grade solder wire. It uses a high-purity, eutectic tin/copper/cobalt alloy that exceeds J-STD-006C and meets ASTM B 32 purity specifications. It is complemented with a rosin activated, medium activity flux that is classified as ROM1 according to J-STD-004B.

This solder is a great lead-free alternative to leaded solders. It generally provides better wetting, contact angle, flow, and visual appearance than typical Sn63/Pb37 no clean solders, while still delivering excellent performance characteristics. It offers superior solder penetration into plated through holes and surface mount interconnects. Further, it is a suitable replacement for SAC305 solder since the 494x forms brighter, shinier, and less grainy joints. Furthermore, it is less expensive than SAC305.

The 4942–4944 solders achieve a consistent solder and flux percentage through a state-of-the-art, extrusion, wire-drawing machine. This machine continually monitors the wire to prevent voids and ensure consistency, providing a top-grade solder wire.

### Benefits & Features

- **Lead free eutectic alloy**  
(liquidus = solidus temperature)
- **Alloy exceeds J-STD-006C and meets ASTM B 32 purity requirements**
- **Flux meets J-STD-004B**
- **Fast wetting**
- **Fast flowing**
- **Non-corrosive**
- **Non-conductive residues**

#### COMPLIANCE

- ✓ Dobb Frank ([DRC conflict free](#))
- ✓ REACH ([compliant](#))
- ✓ RoHS ([compliant](#))

### Wire Sizes Availability

<i>Cat No.</i>	<i>Std. Wire Gauge</i>	<i>Diameter</i>		<i>Packaging</i>	<i>Sizes</i>
4942	25	0.51 mm	0.020 in	Spool	¼ or 1 lb
4944	21	0.81 mm	0.032 in	Spool	¼ or 1 lb

### General Flux Parameters

<i>Properties</i>	<i>Value</i>
Residue Removal	Not required
Flux Percentage	2.2%
Flux feature	Fast wetting, fast flowing, non-conductive
Shelf life	5 y

*Continued on the next page*

### Flux Core Properties

The rosin activated flux wets rapidly and is fast flowing. It is also non-conductive and non-corrosive.

<b>Physical Properties</b>	<b>Method</b>	<b>Value</b>
Flux Classification	J-STD-004B MIL-F-14256F	ROM1 RA
Flux Type		Rosin
%Halides		0.5–2.0%
Color	—	Amber solid
Softening Point of Flux Extract		80 °C [176 °F]
Acid Number (mgKOH/g sample)	IPC-TM-650 2.3.13	150–160
Silver Chromate—Chlorides + Bromides	IPC-TM-650 2.3.33	Detection
Surface Insulation Resistance (SIR)	IPC-TM-650 2.6.3.3	$>1.0 \times 10^9 \Omega$
Corrosion Test	IPC-TM-650 2.6.15	Non-corrosive
Cleaning Requirements	—	Application dependent <sup>a)</sup>

a) Since there is only 2.2% flux, removal of residue can be considered optional for some applications.

### Sn100e Alloy Typical Literature Properties

<b>Physical Properties</b>	<b>Value <sup>a)</sup></b>
Color	Silvery-white metal
Density @26 °C [78 °F]	7.4 g/cm <sup>3</sup>
Tensile Strength	28 N/mm <sup>2</sup> [4 100 lb/in <sup>2</sup> ]
Elongation	27%
Shear Strength	~20 N/mm <sup>2</sup> [~2 900 lb/in <sup>2</sup> ]
<b>Electrical Properties</b>	<b>Value</b>
Volume Resistivity	12.3 μΩ·cm
Electrical Conductivity <sup>b)</sup>	15% IACS

a) N/mm<sup>2</sup> = mPa; lb/in<sup>2</sup> = psi;

b) International Annealed Copper Standard: 100% give  $5.8 \times 10^7$  S/m.

*Continued on the next page*


Continued...

<b>Thermal Properties</b>	<b>Value</b>
Melting Point, Solidus	228 °C [442 °F]
Melting Point, Liquidus	228 °C [442 °F]
Tip Temperature Upper Limit	Do not exceed 425 °C [800 °F]
Coefficient of Thermal Expansion (CTE) <sup>c)</sup>	23.5 ppm/°C
Thermal Conductivity	82 W/(m·K)
Specific Heat Capacity	294 J/(kg·K)

NOTE: This table present typical literature values for Sn99.5/Cu0.5/Co alloys.

c) CTE for pure tin; unit conversions: ppm/°C =  $\mu\text{m}/(\text{m}\cdot\text{K}) = \text{in}/\text{in}/\text{°C} \times 10^{-6} = \text{unit}/\text{unit}/\text{°C} \times 10^{-6}$

### Solder Alloy Composition

<b>Properties</b>	<b>Value</b>	<b>Properties</b>	<b>J-STD-006C</b>	<b>4942-4944 Values</b>
<i>MAIN INGREDIENTS</i>	<i>COMPOSITION</i>	<i>IMPURITIES</i> <sup>a)</sup>	<i>REQUIREMENTS</i>	<i>SPECIFICATIONS</i>
Sn	99.3 to 99.7%	Sb	≤0.20% Max	≤0.025% Max
Cu	0.49 to 0.51%	Ag	≤0.10% Max	≤0.001% Max
Co	<0.1%	Bi	≤0.10% Max	≤0.01% Max
		In	≤0.10% Max	≤0.01% Max
		Pb	≤0.07% Max	≤0.05% Max
		Au	≤0.05% Max	≤0.0002% Max
		As	≤0.05% Max	≤0.0035% Max
		Fe	≤0.02% Max	≤0.005% Max
		Ni	≤0.01% Max	≤0.006% Max
		Al	≤0.005% Max	≤0.001% Max
		Zn	≤0.003% Max	≤0.001% Max
		Cd	≤0.002% Max	≤0.001% Max

a) Exceeds the requirements of J-STD-006C and meets ASTM B 32.

### Storage

Protect from direct heat or sunlight. Store between 18 to 27 °C [65 to 80 °F].

### Cleaning

The flux residue does not need to be removed for typical applications. If removal is desired, a solvent system like the *MG 4140* can be used. For best results, warm the cleaning solution to about 40 °C [104 °F].

### Health and Safety

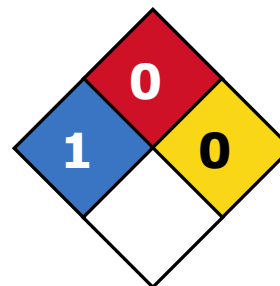
Please see the 4942-4944 **Safety Data Sheet** (SDS) for more details on transportation, storage, handling and other security guidelines.

**Health and Safety:** Avoid breathing fumes. Wash hands thoroughly after use. Do not ingest.

#### HMIS® RATING

<b>HEALTH:</b>	* <b>1</b>
<b>FLAMMABILITY:</b>	<b>0</b>
<b>PHYSICAL HAZARD:</b>	<b>0</b>
<b>PERSONAL PROTECTION:</b>	

#### NFPA® 704 CODES



*Approximate HMIS and NFPA Risk Ratings Legend:*

0 (Low or none); 1 (Slight); 2 (Moderate); 3 (Serious); 4 (Severe)

### Soldering Instructions

#### To achieve best hand-soldering results

1. Set the tip temperature between 370-425 °C [700-800 °F].
2. Place the solder tip in contact with the joint connection (lead/pad surface) at an angle of around 50° to heat the parts to be soldered.
3. While the soldering tip is applied, touch the solder wire to the opposite side of the soldering joint, not to the soldering tip.
4. Immediately after the solder has flowed around the whole heated connection, remove the solder wire and remove soldering tip from connection.

**TIP!** Do not move the connection while the solder is cooling.

**WARNING!** Avoid putting too much or too little solder.

**ATTENTION!** To avoid damage, do not overheat electrical component.

### Packaging and Supporting Products

<i>Cat. No.</i>	<i>Form</i>	<i>Packaging</i>	<i>Net Weight</i>	
<b>4942-112G</b>	Solid wire	Spool	112 g	0.25 lb
<b>4942-454G</b>	Solid wire	Spool	454 g	1.0 lb
<b>4944-112G</b>	Solid wire	Spool	112 g	0.25 lb
<b>4944-454G</b>	Solid wire	Spool	454 g	1.0 lb



# Sn100e RA Solder Wire 4942–4944 Technical Data Sheet

ISO 9001:2008 Registered Quality System. Burlington, Ontario, CANADA SAI Global File: 004008

4942–4944

## Technical Support

Contact us regarding any questions, improvement suggestions, or problems with this product. Application notes, instructions, and FAQs are located at [www.mgchemicals.com](http://www.mgchemicals.com).

Email: [support@mgchemicals.com](mailto:support@mgchemicals.com)

Phone: +(1) 800-340-0772 (Canada, Mexico & USA)

+ (1) 905-331-1396 (International)

+ (44) 1663 362888 (UK & Europe)

Fax: +(1) 905-331-2862 or +(1) 800-340-0773

Mailing address: **Manufacturing & Support**  
1210 Corporate Drive  
Burlington, Ontario, Canada  
L7L 5R6

**Head Office**  
9347–193rd Street  
Surrey, British Columbia, Canada  
V4N 4E7

## Warranty

*M.G. Chemicals Ltd.* warrants this product for 12 months from the date of purchase by the end user. *M.G. Chemicals Ltd.* makes no claims as to shelf life of this product for the warranty. The liability of *M.G. Chemicals Ltd.* whether based on its warranty, contracts, or otherwise shall in no case include incidental or consequential damage.

## Disclaimer

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. *M.G. Chemicals Ltd.* does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.